

**REPLY UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2800**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>In Re Application of:</b> Angyal <i>et al.</i>	<b>Conf. No.:</b> 4705
<b>Serial No.:</b> 10/710,706	<b>Art Unit:</b> 2813
<b>Filed:</b> 07/29/2004	<b>Docket No.:</b> FIS920040028US1 (IBMF-0053)
	<b>Examiner:</b> Monica D. Harrison

**Title:** INTERLEVEL DIELECTRIC  
LAYER AND METAL LAYER  
SEALING

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AFTER FINAL REQUEST FOR RECONSIDERATION**

Sir:

**INTRODUCTORY COMMENTS**

In response to the Final Office Action of February 22, 2006, please re-consider the rejections based on the following remarks.